



TITLE: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6
INVENTORS NAME: Krishna Seshan et al.
SERIAL NO.: 10/052089

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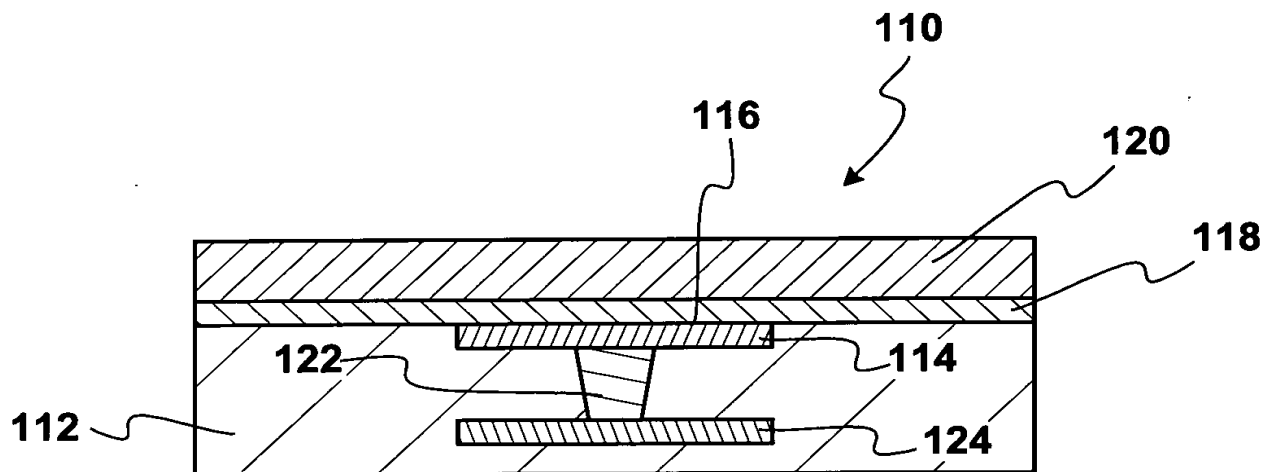


Fig. 1

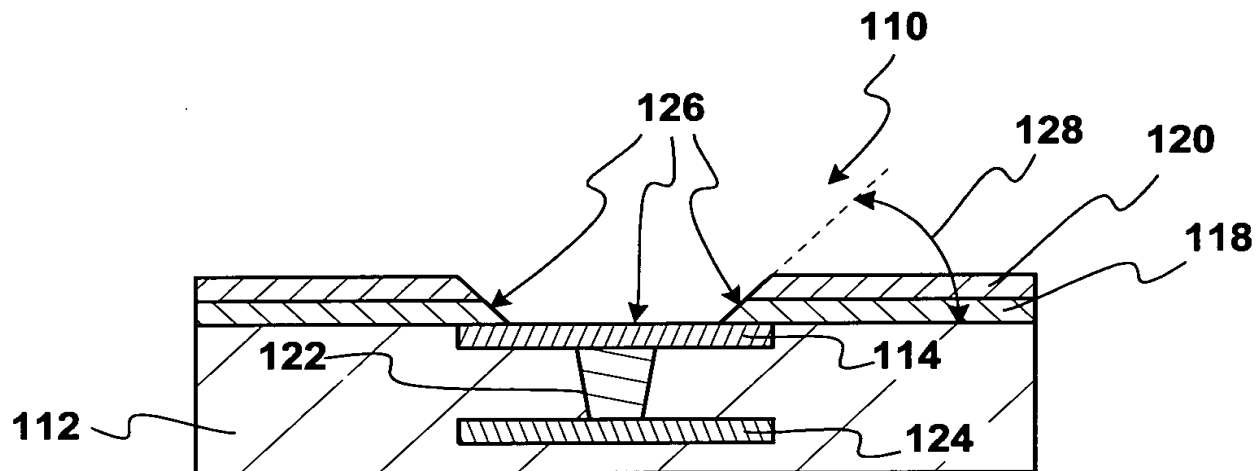


Fig. 2

Fig. 4

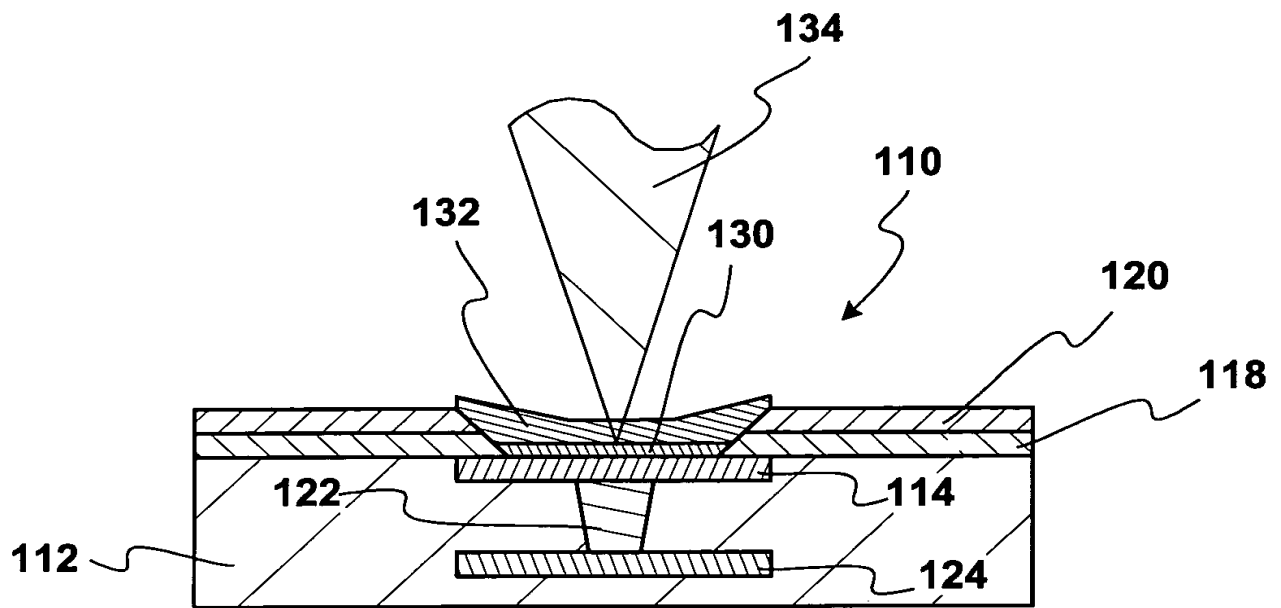


Fig. 5

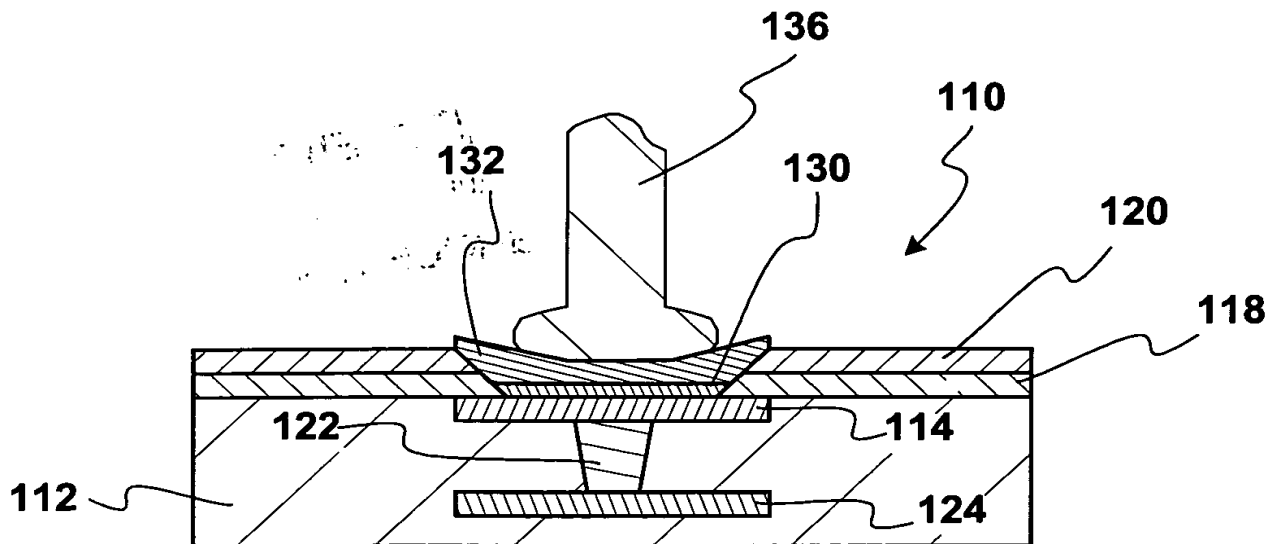


Fig. 6

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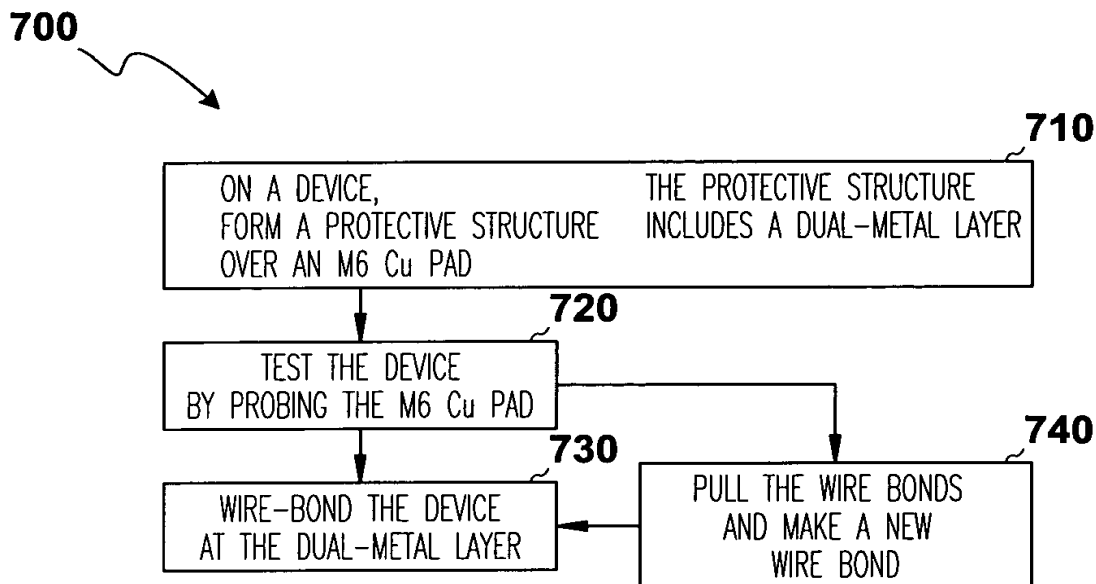


Fig. 7

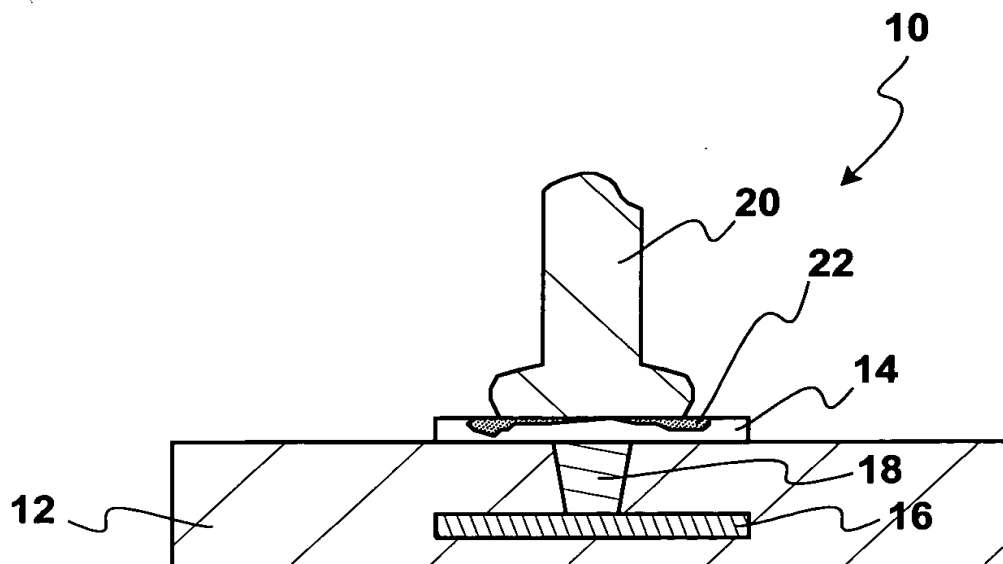


Fig. 8
(Prior Art)